







DUAL 20V PNP LOW SATURATION SWITCHING TRANSISTOR

Features and Benefits

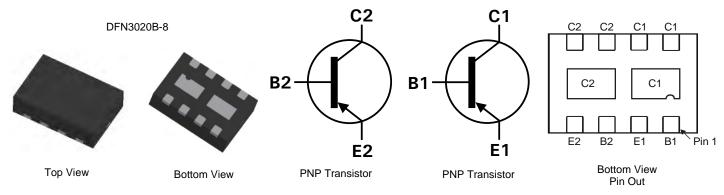
- BV_{CEO} > -20V;
- I_C = -3.5A Continuous Collector Current
- $R_{SAT} = 64 \text{ m}\Omega$ for Low Equivalent On Resistance
- Low Saturation Voltage (-220mV @ -1A)
- hFE characterized up to -6A for high current gain holds up
- Dual NPN saving footprint and component count
- Low profile 0.8mm high package for thin applications
- R_{0JA} efficient, 40% lower than SOT26
- 6mm² footprint, 50% smaller than TSOP6 and SOT26
- Lead-Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: DFN3020B-8
- Case material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Rating 94V-0
- Terminals: Pre-Plated NiPdAu leadframe.
- Nominal package height: 0.8mm
- Moisture Sensitivity: Level 1 per J-STD-020
- Solderable per MIL-STD-202, Method 208
- Weight: 0.013 grams (approximate)

Applications

- · Battery charging circuits
- · Load disconnect switches
- DC-DC converters
- Motor drive
- LED backlighting circuits
- Portable applications



Equivalent Circuit

Ordering Information (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTD718MCTA	D22	7	8	3,000

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For Packaging Details, go to our website at http://www.diodes.com.

Marking Information



D22 = Product type Marking Code Top view, dot denotes Pin 1



Maximum Ratings @ T_A = 25°C unless otherwise specified

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	-25	
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Base Voltage	V _{EBO}	-7	
Peak Pulse Current	I _{CM}	-6	
Continuous Collector Current (Notes 4 and 7)	Ic	-3.5	Α
Base Current	lΒ	-1	

Thermal Characteristics @ $T_A = 25^{\circ}C$ unless otherwise specified

Characteristic	Symbol	Value	Unit		
	(Notes 4 & 7)		1.5 12		
Power Dissipation	(Notes 5 & 7)	P _D	2.45 19.6	W mW/°C	
Linear Derating Factor	(Notes 6 & 7)		1.13 8		
	(Notes 6 & 8)		1.7 13.6		
	(Notes 4 & 7)		83.3		
The arms of Decistance . It was then to Archive	(Notes 5 & 7)	$R_{ hetaJA}$	51.0		
Thermal Resistance, Junction to Ambient	(Notes 6 & 7)		111	°C/W	
	(Notes 6 & 8)	1	73.5		
Thermal Resistance, Junction to Lead	(Notes 7 & 9)	$R_{ heta JL}$	17.1		
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C	

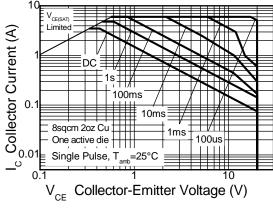
Notes:

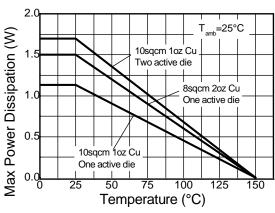
- 4. For a dual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is →. Lot a qual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half.
 5. Same as note (4), except the device is measured at t <5 sec.
 6. Same as note (4), except the device is surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper.
 7. For a dual device with one active die.
 8. For dual device with 2 active die running at equal power.
 9. Thermal resistance from junction to solder point (at the cond of the collector lead).

- 9. Thermal resistance from junction to solder-point (at the end of the collector lead).



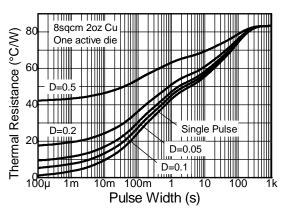
Thermal Characteristics

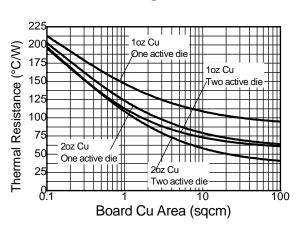




Safe Operating Area

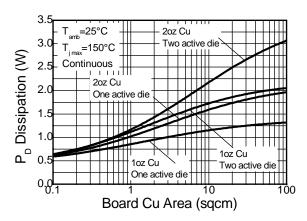






Transient Thermal Impedance

Thermal Resistance v Board Area



Power Dissipation v Board Area



Electrical Characteristics @T_A = 25°C unless otherwise specified

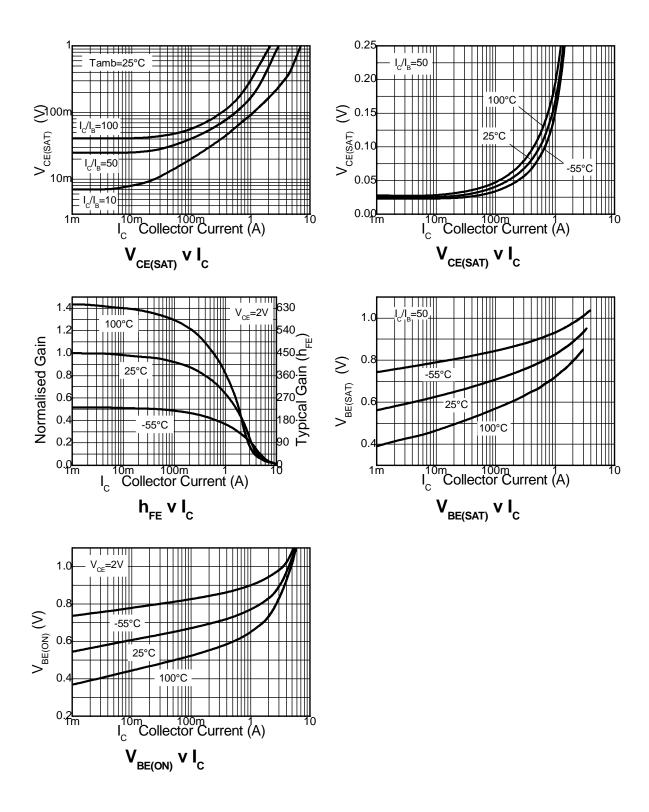
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-25	-35	-	V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 10)	BV _{CEO}	-20	-25	-	V	$I_C = 10mA$
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	8.5	-	V	$I_E = -100 \mu A$
Collector Cutoff Current	Ісво	-	-	-100	nA	V _{CB} = -20V
Emitter Cutoff Current	I _{EBO}	-	-	-100	. nA	$V_{EB} = -6V$
Collector Emitter Cutoff Current	I _{CES}	-	-	-100	nA	V _{CES} = -16V
		300	475	-		$I_C = -10 \text{mA}, V_{CE} = -2 \text{V}$
Static Forward Current Transfer Datic (Note 10)	L .	300	450	-		$I_C = -100 \text{mA}, V_{CE} = -2 \text{V}$
Static Forward Current Transfer Ratio (Note 10)	h _{FE}	150	230	-	-	I _C = -2A, V _{CE} = -2V
		15	30	-		I _C = -6A, V _{CE} = -2V
	V _{CE(sat)}	-	-19	-30	mV	$I_C = -0.1A$, $I_B = -10mA$
		-	-170	-220		$I_C = -1A$, $I_B = -20mA$
Collector-Emitter Saturation Voltage (Note 10)		-	-190	-250		$I_C = -1.5A$, $I_B = -50mA$
		-	-240	-350		$I_C = -2.5A$, $I_B = -150mA$
		-	-225	-300		$I_C = -3.5A$, $I_B = -350m$
Base-Emitter Turn-On Voltage (Note 10)	V _{BE(on)}	-	-0.87	-0.95	V	$I_C = -3.5A$, $V_{CE} = -2V$
Base-Emitter Saturation Voltage (Note 10)	V _{BE(sat)}	-	-1.01	-1.12	V	$I_C = -3.5A$, $I_B = -350mA$
Output Capacitance	$C_{ m obo}$	-	21	30	pF	$V_{CB} = 10V, f = 1MHz$
Transition Frequency	fτ	150	180	-	MHz	$V_{CE} = -10V, I_{C} = -50mA,$ f = 100MHz
Turn-On Time	t _{on}	-	40	-	ns	V _{CC} = -10V, I _C = 1A
Turn-Off Time	t _{off}	-	670	_	ns	$I_{B1} = I_{B2} = 20 \text{mA}$

Notes: 10. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%



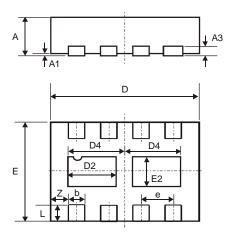


Typical Electrical Characteristics



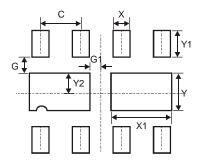


Package Outline Dimensions



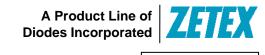
DFN3020B-8					
Dim	Min	Max	Тур		
Α	0.77	0.83	0.80		
A1	0	0.05	0.02		
A3	-	-	0.15		
b	0.25	0.35	0.30		
D	2.95	3.075	3.00		
D2	0.82	1.02	0.92		
D4	1.01	1.21	1.11		
е	-	-	0.65		
Е	1.95	2.075	2.00		
E2	0.43	0.63	0.53		
L	0.25	0.35	0.30		
Z	-	-	0.375		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
С	0.650
G	0.285
G1	0.090
X	0.400
X1	1.120
Υ	0.730
Y1	0.500
Y2	0.365





ZXTD718MC

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